

Selection Guide

Part No.	Dice	Lens Type	Iv (ucd) [1] @ 10mA		Description
			Min.	Typ.	
KCPSA04-101	High Efficiency Red (GaAsP/GaP)	WHITE DIFFUSED	800	3200	Common Anode, Rt. Hand Decimal.

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	High Efficiency Red	627		nm	I _F =20mA
λ_D [1]	Dominant Wavelength	High Efficiency Red	625		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	High Efficiency Red	45		nm	I _F =20mA
C	Capacitance	High Efficiency Red	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	High Efficiency Red	2.0	2.5	V	I _F =20mA
I _R	Reverse Current	High Efficiency Red		10	uA	V _R =5V

Notes:

1.Wavelength: +/-1nm.

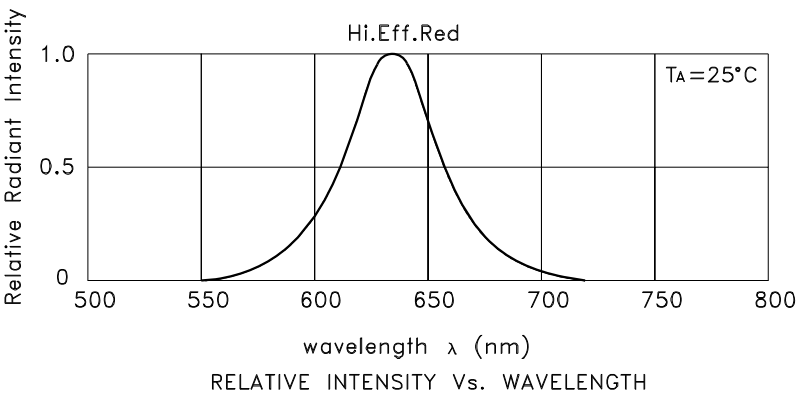
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

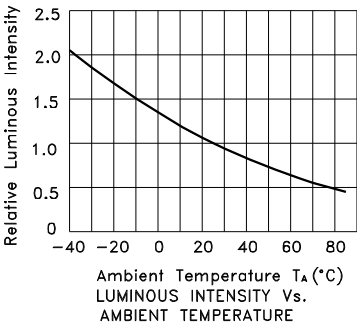
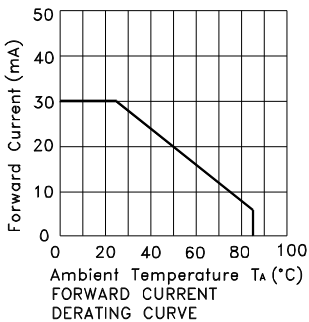
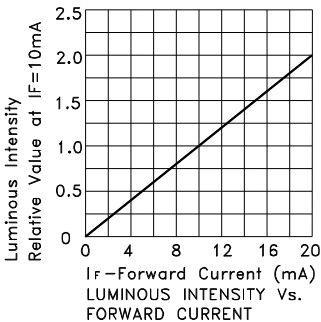
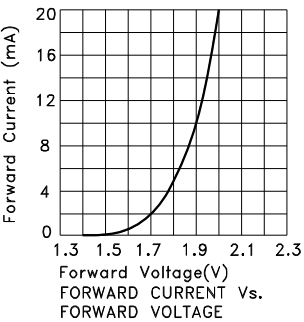
Parameter	High Efficiency Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

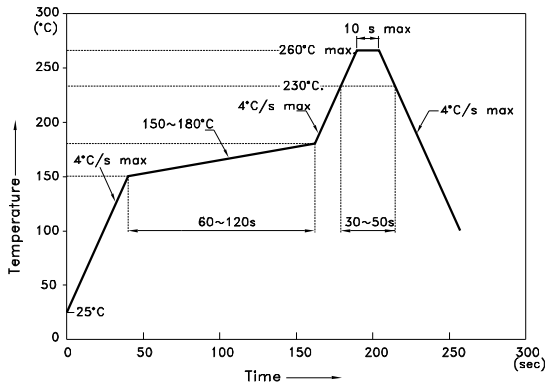


High Efficiency Red KCPSA04-101



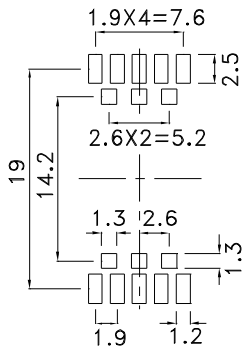
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Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.15)



Tape Specifications (Units : mm)

